

Amendments to the Claims

1 - 24. (Canceled)

25. (Currently amended) A semiconductor device package, comprising:

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a semiconductor device having diced edges ~~formed by a dicing operation~~;
a dielectric substrate having diced edges ~~formed by said dicing operation~~;
a metal layer formed between said semiconductor device and said dielectric substrate, said metal layer having diced edges formed by said dicing operation;
a ball grid array on said dielectric substrate, said dielectric substrate and said metal layer being located between said semiconductor device and said ball grid array; and
electrical connections between said semiconductor device and said ball grid array,
wherein said metal layer has a stiffness sufficient to enable simultaneous dicing of said semiconductor device edges, said dielectric substrate edges, and said metal layer edges, so as to provide said package with aligned edges.

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26. (Original) The package of claim 25, wherein said metal layer provides a ground plane for said electrical connections.

27. (Canceled)

28. (Original) The package of claim 25, wherein said metal layer is arranged to dissipate heat from said semiconductor device.

29. (Original) The package of claim 25, wherein said metal layer comprises copper.

30. (Previously amended) The package of claim 25, wherein said connections comprise wire bonds.

sub E1
31. (Original) The package of claim 25, wherein said connections comprise
conductive vias.

Cont'd
32. (Original) The package of claim 31, wherein said connections further comprise
conductive traces on opposite sides of said substrate.

33. (Original) The package of claim 32, further comprising solder bumps on said
semiconductor device, said bumps being connected to said traces.

34. (Previously amended) The package of claim 25, further comprising an insulative
solder mask for covering said dielectric substrate.

35 – 38. (Canceled)
